

AMENDMENTS TO THE CLAIMS

The following listing of claims replaces all prior versions, and listings, of claims in this application.

Claim 1. (Currently Amended) A laminate for an HDD suspension comprising a stainless steel layer, a polyimide resin layer, and a conductive layer, wherein a thickness of the conductive layer is 10 μm or less, and a surface roughness (Ra)(Rz) of the conductive layer is 0.150.45 μm or less.

Claim 2. (Original) The laminate for an HDD suspension as described in claim 1, wherein the conductive layer is an alloyed copper foil having a strength of 500 MPa or more and an electric conductivity of 65 % or more.

Claim 3. (Canceled)

Claim 4. (Currently Amended) A production process of a laminate for an HDD suspension, wherein comprising the steps of:

producing a laminate comprising a stainless steel layer, a polyimide resin layer, and a conductive layer is produced by using a conductive layer having a thickness of larger than 10 μm ; and

thereaftersubjecting only the conductive layer of the laminateis subjected to chemical etching to thereby reduce [[a]]the thickness of the conductive layer to 10 μm or less;
wherein a surface roughness (Rz) of the conductive layer after the chemical etching is 0.45 μm or less.

Claim 5. (Original) The production process of a laminate for an HDD suspension as described in claim 4, wherein the conductive layer is an alloyed copper foil having a strength of 500 MPa or more and an electric conductivity of 65 % or more.

Claim 6. (Original) The production process of a laminate for an HDD suspension as described in claim 4, wherein the laminate after subjected to chemical etching is subjected to supersonic treatment in an alkaline solution.

Claim 7. (Original) The production process of a laminate for an HDD suspension as described in claim 5, wherein the laminate after subjected to chemical etching is subjected to supersonic treatment in an alkaline solution.

Claim 8. (Previously Presented) The production process of a laminate for an HDD suspension as described in claim 4, wherein the conductive layer after subjected to chemical etching has a surface roughness (Ra) of 0.15 μm or less.

Claim 9. (Previously Presented) The production process of a laminate for an HDD suspension as described in claim 5, wherein the conductive layer after subjected to chemical etching has a surface roughness (Ra) of 0.15 μm or less.

Claim 10. (Previously Presented) The production process of a laminate for an HDD suspension as described in claim 6, wherein the conductive layer after subjected to chemical etching has a surface roughness (Ra) of 0.15 μm or less.